

[10191/1690]

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Inventor(s) : Volker BECKER et al.  
Serial No. : To Be Assigned  
Filed : Herewith  
For : DEVICE AND METHOD FOR ETCHING A  
SUBSTRATE USING AN INDUCTIVELY  
COUPLED PLASMA #61/2 .A  
Examiner : To Be Assigned  
Art Unit : To Be Assigned

Assistant Commissioner for Patents  
Washington, D.C. 20231

**PRELIMINARY AMENDMENT**

SIR:

Kindly amend the above-identified application before examination as set forth below.

**IN THE SPECIFICATION:**

On page 1, line 5, insert: --FIELD OF THE INVENTION--.

A1

On page 1, line 11, delete "Background Information" and insert:

--DESCRIPTION OF RELATED ART--.

A2

On page 3, line 7, delete "Advantages of the Invention" and insert:

--SUMMARY OF THE INVENTION--.

A3

On page 7, line 7, delete "Drawings" and insert:

--BRIEF DESCRIPTION OF THE DRAWINGS--.

A4

Page 7, line 26, delete "Exemplary Embodiments" and insert:

--DETAILED DESCRIPTION OF THE INVENTION--.

A5